

Application No.: 09884,844
Amendment dated: March 1, 2006
Reply to Office Action of December 1, 2005
Attorney Docket No.: 1066us

This listing of claims will replace all prior versions and listings of claims in this application:

a.) Listing of Claims

1. (currently amended) An optoelectronic hermetic package, comprising:
a frame defining a hermetic boundary; ~~and~~
an electrical feedthrough assembly on the frame ~~1) providing~~ including: 1)
electrical connections between signal wire bond areas within the hermetic boundary and electrical contact areas outside the hermetic boundary; and
2) ground wire bond areas within the hermetic boundary that are electrically connected to each other; and
conductive plugs extending between a top of the feedthrough assembly and the frame, the ground wire bond areas being located on a top of the conductive plugs.
2. (original) A package as claimed in claim 1, further comprising an array of leads extending from electrical contact areas away from the frame.
3. (original) A package as claimed in claim 2, wherein the leads extend laterally relative to the frame.
4. (previously presented) A package as claimed in claim 2, wherein the leads are pins that extend vertically relative to the frame.
5. (original) A package as claimed in claim 1, wherein at least some of the ground wire bond areas are located between two of the signal wire bond areas on the feedthrough assembly.
6. (original) A package as claimed in claim 1, wherein the ground wire bond areas are interdigitated with signal wire bond areas.

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7. (cancelled)
8. (cancelled)
9. (currently amended) An optoelectronic hermetic package, comprising:
a frame defining a hermetic boundary;
an electrical feedthrough assembly on the frame including: 1) electrical
connections between signal wire bond areas within the hermetic boundary
and electrical contact areas outside the hermetic boundary; and 2) ground
wire bond areas within the hermetic boundary that are electrically
connected to each other; and
~~A package as claimed in claim 1, further comprising~~ conductive plugs
extending between a top of the feedthrough assembly and a bus through
the assembly, the ground wire bond areas being located on a top of the
conductive plugs.
10. (new) A package as claimed in claim 9, further comprising an array of leads
extending from electrical contact areas away from the frame.
11. (new) A package as claimed in claim 10, wherein the leads extend laterally
relative to the frame.
12. (new) A package as claimed in claim 10, wherein the leads are pins that
extend vertically relative to the frame.
13. (new) A package as claimed in claim 9, wherein at least some of the ground
wire bond areas are located between two of the signal wire bond areas on the
feedthrough assembly.
14. (new) A package as claimed in claim 9, wherein the ground wire bond areas
are interdigitated with signal wire bond areas.